



24-Pin SOIC-to-22-Pin 0.400" DIP

FEATURES

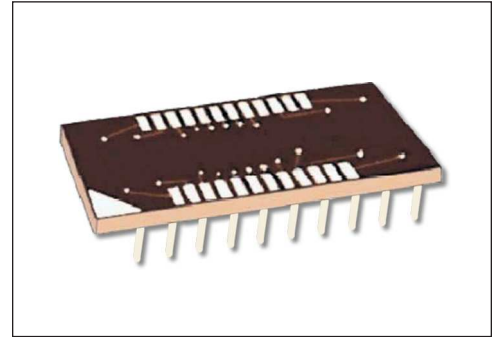
- A cost-effective means of upgrading to SOIC without changing your PCB layout.

GENERAL SPECIFICATIONS

- BOARD MATERIAL: 0.062 thick FR-4 with 1-oz. Cu traces, both sides
- PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- PIN PLATING: 200 μ [5.08 μ] Sn/Pb 93/7 per ASTM B579-73 over 100 μ [2.54 μ] Ni per SAE AMS-QQ-N-290
- OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS

- SUGGESTED PCB HOLE SIZE: 0.028 $\pm$ 0.003 [0.71 $\pm$ 0.08] dia.



CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: $\pm$ 0.005 [0.13] UNLESS OTHERWISE SPECIFIED

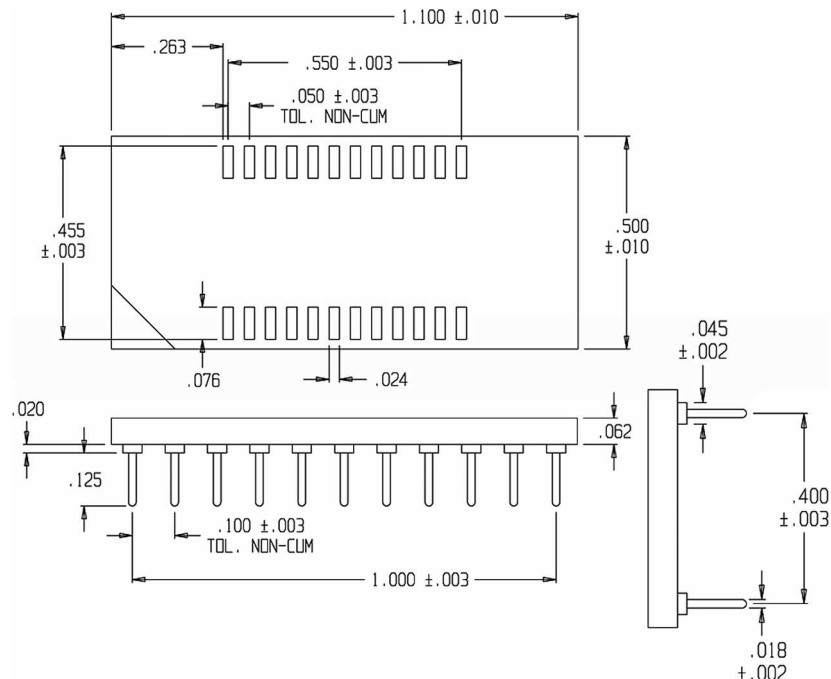
PINS 11 AND 14 NOT CONNECTED ON SOIC

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS

ORDERING INFORMATION

22-304504-18-P

Optional
Panelized Version



ARIES
ELECTRONICS, INC.

Bristol, PA 19007-6810 USA
TEL (215) 781-9956 • FAX (215) 781-9845
WWW.ARIESELEC.COM • INFO@ARIESELEC.COM

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